Technical Data Sheet

1521

1521 is two components adhesive that can cure fast at room temperature providing excellent sealing and bonding.

This material is recommended for the potting of electronic components, typically for junction box on PV modules.

Technology / Base	Silicone
Type of Product	Adhesive
Components	Two components
Curing	Room temperature cure
Appearance / Color	White
Consistency	Viscous Liquid

Features and Benefits

- Fast cure at room temperature, excellent deep section cure.
- Easy handing due to 6:1mixing ratio.
- Excellent adhesion to various substrates.
- Suitable for automated dispensing.
- Excellent electrical performance.
- Excellent resistance to hot damp conditioning.

Curing Profile

Recommended cure:

- (23±2)℃，(50±5)%RH for 7 days

Contact HB Fuller technical support for additional curing recommendations.

Application Instructions

1. Part A should be blended thoroughly before mix with Part B in order to make filling material distribute evenly.
2. Mix evenly according to the ratio.
3. Pot the mixed material.
4. Recommended using automatic dispensing equipment to applying the potting compound.

Storage Conditions

Product shall be ideally stored in a cool, dry area in unopened containers at room temperature.
Keep away from children.
Shelf Life: 6 months from date of manufacture.

Typical Packaging

Please contact your local Sales Office for available packaging options.

Disposal Advice

Please refer to the MSDS for disposal instructions.

Safety Advice

Please refer to the MSDS for safety advice.

Technical Data

Rheology	Value	Condition/Method
Viscosity Resin	7000 mPa·s	GB/T 2794
Viscosity Activator	25 mPa·s	GB/T 2794
Viscosity Mixed	3000 mPa·s	GB/T 2794
Density		
Mixed Density	1.40 g/cm^3	GB/T 13354
Mix Ratio		
Volumetric Mix Ratio	4:1	
Weight Mix Ratio	6:1	
Curing		
Flash Point	＞93℃	GB/T 5208
Working Time	8 minutes	Viscosity higher than 30000mPa·s.
Gel Time	60 minutes	The glue does not flow.
Cured Mechanical Properties		
Hardness	40 ShoreA	GB/T 531
Tensile Strength	1.2 MPa	GB/T 528
Elongation to Break	110%	GB/T 528
Thermal Indication		
Thermal Service Range	(–50～150)℃	
Heat-Conducting Property		
Thermal Conductive	0.30 W/m·K	DIN EN 821
Electrical Property		
Volume Resistivity	1.0×10^{15} Ω·cm	GB/T 1692
Breakdown Strength	23kV/mm	GB/T 1695
Damp-Heat Aging Property (85℃,85%RH for 1000h)		
Volume Resistivity	1.0×10^{15} Ω·cm	GB/T 1692

Date Modified: 25/05/2018

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